PACKAGE-ON-PACKAGE SEMICONDUCTOR STRUCTURE

ABSTRACT

A semiconductor package that includes a substrate having first and second major surfaces is presented. The package includes a plurality of landing pads and a semiconductor die disposed on the first major surface. A molded cap is disposed on the first surface to encapsulate the die and substrate. The landing pads are covered when the cap is molded. Package interconnects are coupled to the landing pads. The package interconnects are exposed by the cap to facilitate package stacking.

Fig. 1(b)